

## Mirra 3400



The Applied Mirra CMP system is an automated system that uses a combination of chemistry and abrasion under controlled conditions to remove specific amounts of material from wafer surfaces. The Mirra 3400 stand alone delivers industry-leading 200 mm CMP on all polishing applications.

Wafers are processed dry-in and wet-out and the system can accommodate up to four 25-wafer cassettes, attaching a recipe and automatically performing a sequence to each wafer.

The system's polishing head optimizes uniformity across the wafer by tuning film removal rate to match specific slurry chemistries to control dishing and erosion in high performance polishing applications.

For AMAT refurbished equipment:  
[info@entrepix.com](mailto:info@entrepix.com)

For AMAT spare parts and upgrades:  
[parts@entrepix.com](mailto:parts@entrepix.com)

For AMAT equipment service /  
maintenance:  
[service@entrepix.com](mailto:service@entrepix.com)

Or Call:  
602-426-8677 (Sales)

### **Preventative Maintenance Program**

#### **Overview**

- General Clean and Inspections
- Clean and Lubricate All Rails and Drives
- Baseline Equipment
- Load Calibrations
- Platen Run Out
- Arm Sweet Calibrations
- Carrier Run Out
- Down Force Calibration
- Back Pressure Calibrations
- Pad Conditioner Operations Check
- Unload Calibrations
- Tool-Specific Issues Addressed